2SD1264, 2SD1264A

Silicon NPN triple diffusion planar type

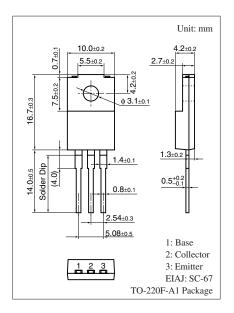
For low-frequency power amplification For TV vertical deflection output Complementary to 2SB0940, 2S0940A

■ Features

- ullet High collector-emitter voltage (Base open) V_{CEO}
- Large collector power dissipation P_C
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (En	V _{CBO}	200	V	
Collector-emitter voltage	2SD1264	V _{CEO}	150	V
(Base open)	2SD1264A		180	
Emitter-base voltage (Col	V _{EBO}	6	V	
Collector current	I_{C}	2	A	
Peak collector current	I_{CP}	3	A	
Collector power	$T_C = 25^{\circ}C$	P _C	30	W
dissipation		2.0		
Junction temperature	T _j	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



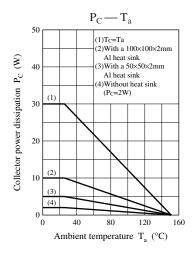
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

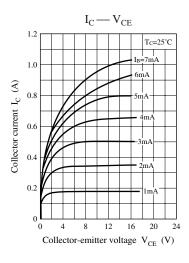
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Em	itter open)	V_{CBO}	$I_C = 50 \ \mu A, I_E = 0$	200			V
Collector-emitter voltage	2SD1264	V_{CEO}	$I_C = 5 \text{ mA}, I_B = 0$	150			V
(Base open)	2SD1264A			180			
Emitter-base voltage (Colle	ctor open)	V_{EBO}	$I_E = 500 \ \mu A, \ I_C = 0$	6			V
Base-emitter voltage		V_{BE}	$V_{CE} = 10 \text{ V}, I_{C} = 400 \text{ mA}$			1.0	V
Collector-base cutoff current (E	mitter open)	I_{CBO}	$V_{CB} = 200 \text{ V}, I_E = 0$			50	μΑ
Emitter-base cutoff current (Col	lector open)	I_{EBO}	$V_{EB} = 4 \text{ V}, I_C = 0$			50	μΑ
Forward current transfer rat	io	h _{FE1} *	$V_{CE} = 10 \text{ V}, I_{C} = 150 \text{ mA}$	60		240	_
		h _{FE2}	$V_{CE} = 10 \text{ V}, I_{C} = 400 \text{ mA}$	50			
Collector-emitter saturation	voltage	V _{CE(sat)}	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$			1.0	V
Transition frequency		f_T	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 1 \text{ MHz}$		20		MHz

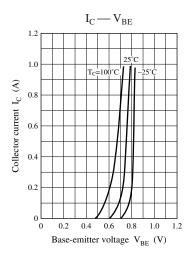
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

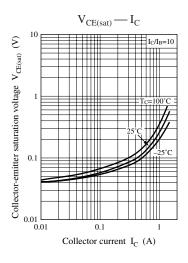
2. *: Rank classification

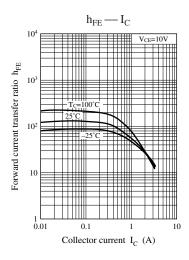
Rank	Q	Р		
h _{FE1}	60 to 140	100 to 240		

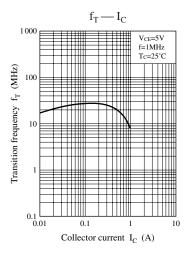


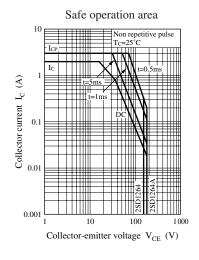


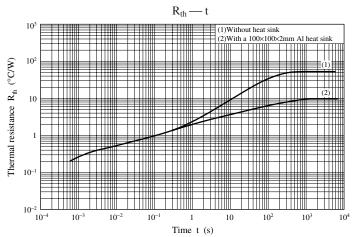












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